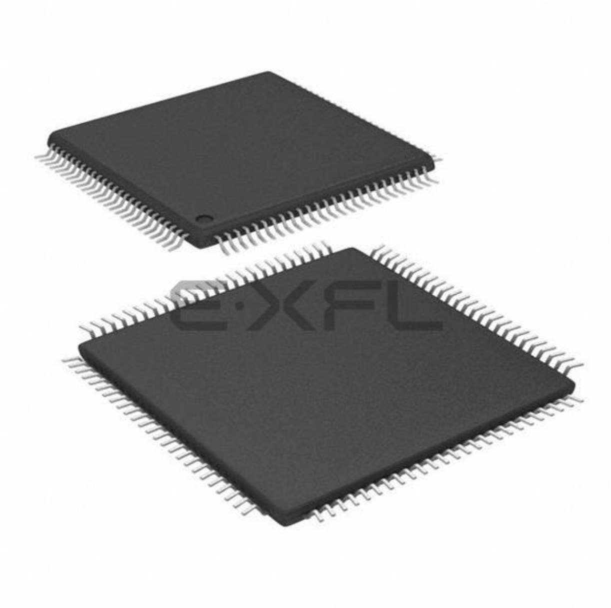


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	CANbus, I²C, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	85
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx564f128lt-i-pt

TABLE 3: PIC32MX7XX USB, ETHERNET, AND CAN FEATURES

USB, Ethernet, and CAN																		
Device	Pins	Program Memory (KB)	Data Memory (KB)	USB	Ethernet	CAN	Timers/Capture/Compare	DMA Channels (Programmable/Dedicated)	UART(2,3)	SPI(3)	I2C(3)	10-bit 1 Msps ADC (Channels)	Comparators	PMP/PSP	JTAG	Trace	Packages(4)
PIC32MX764F128H	64	128 + 12(1)	32	1	1	1	5/5/5	4/8	6	3	4	16	2	Yes	Yes	No	PT, MR
PIC32MX775F256H	64	256 + 12(1)	64	1	1	2	5/5/5	8/8	6	3	4	16	2	Yes	Yes	No	PT, MR
PIC32MX775F512H	64	512 + 12(1)	64	1	1	2	5/5/5	8/8	6	3	4	16	2	Yes	Yes	No	PT, MR
PIC32MX795F512H	64	512 + 12(1)	128	1	1	2	5/5/5	8/8	6	3	4	16	2	Yes	Yes	No	PT, MR
PIC32MX764F128L	100	128 + 12(1)	32	1	1	1	5/5/5	4/6	6	4	5	16	2	Yes	Yes	Yes	PT, PF, BG
PIC32MX775F256L	100	256 + 12(1)	64	1	1	2	5/5/5	8/8	6	4	5	16	2	Yes	Yes	Yes	PT, PF, BG
PIC32MX775F512L	100	512 + 12(1)	64	1	1	2	5/5/5	8/8	6	4	5	16	2	Yes	Yes	Yes	PT, PF, BG
PIC32MX795F512L	100	512 + 12(1)	128	1	1	2	5/5/5	8/8	6	4	5	16	2	Yes	Yes	Yes	PT, PF, BG, TL

Legend: PF, PT = TQFP MR = QFN BG = TFBGA TL = VTLA(5)

Note 1: This device features 12 KB boot Flash memory.

2: CTS and RTS pins may not be available for all UART modules. Refer to the **"Device Pin Tables"** section for more information.

3: Some pins between the UART, SPI and I^2C modules may be shared. Refer to the **"Device Pin Tables"** section for more information.

4: Refer to **Section 34.0 "Packaging Information"** for more information.

5: 100-pin devices other than those listed here are available in the VTLA package upon request. Please contact your local Microchip Sales Office for details.

TABLE 12: PIN NAMES FOR USB, ETHERNET, AND CAN DEVICES

121-PIN TFBGA (BOTTOM VIEW)

L11

L1

A11

PIC32MX764F128L
PIC32MX775F256L
PIC32MX775F512L
PIC32MX795F512L

Note: The TFBGA package skips from row "H" to row "J" and has no "I" row.

A1

Pin #	Full Pin Name	Pin #	Full Pin Name
A1	PMD4/RE4	E2	T4CK/AC2RX(1)/RC3
A2	PMD3/RE3	E3	ECOL/SCK2/U6TX/$\overline{U3RTS}$/PMA5/CN8/RG6
A3	TRD0/RG13	E4	T3CK/AC2TX(1)/RC2
A4	PMD0/RE0	E5	V_{DD}
A5	C2RX(1)/PMD8/RG0	E6	C2TX(1)/ETXERR/PMD9/RG1
A6	C1TX/ETXD0/PMD10/RF1	E7	V_{SS}
A7	V_{DD}	E8	AETXEN/SDA1/INT4/RA15
A8	V_{SS}	E9	RTCC/EMDIO/AEMDIO/IC1/RD8
A9	ETXD2/IC5/PMD12/RD12	E10	$\overline{SS1}$/IC2/RD9
A10	OC3/RD2	E11	AETXCLK/SCL1/INT3/RA14
A11	OC2/RD1	F1	$\overline{MCLR}$
B1	No Connect (NC)	F2	ERXDV/AERXDV/ECRSDV/AECRSDV/SCL4/SDO2/U3TX/PMA3/CN10/RG8
B2	AERXERR/RG15	F3	ERXCLK/AERXCLK/EREFCLK/AEREFCLK/$\overline{SS2}$/U6RX/$\overline{U3CTS}$/PMA2/CN11/RG9
B3	PMD2/RE2	F4	ECRS/SDA4/SDI2/U3RX/PMA4/CN9/RG7
B4	PMD1/RE1	F5	V_{SS}
B5	TRD3/RA7	F6	No Connect (NC)
B6	C1RX/ETXD1/PMD11/RF0	F7	No Connect (NC)
B7	V_{CAP}	F8	V_{DD}
B8	PMRD/CN14/RD5	F9	OSC1/CLKI/RC12
B9	OC4/RD3	F10	V_{SS}
B10	V_{SS}	F11	OSC2/CLKO/RC15
B11	SOSCO/T1CK/CN0/RC14	G1	AERXD0/INT1/RE8
C1	PMD6/RE6	G2	AERXD1/INT2/RE9
C2	V_{DD}	G3	TMS/RA0
C3	TRD1/RG12	G4	No Connect (NC)
C4	TRD2/RG14	G5	V_{DD}
C5	TRCLK/RA6	G6	V_{SS}
C6	No Connect (NC)	G7	V_{SS}
C7	ETXCLK/PMD15/CN16/RD7	G8	No Connect (NC)
C8	OC5/PMWR/CN13/RD4	G9	TDO/RA5
C9	V_{DD}	G10	SDA2/RA3
C10	SOSCI/CN1/RC13	G11	TDI/RA4
C11	EMDC/AEMDC/IC4/PMCS1/PMA14/RD11	H1	AN5/C1IN+/V_{BUSON}/CN7/RB5
D1	T2CK/RC1	H2	AN4/C1IN-/CN6/RB4
D2	PMD7/RE7	H3	V_{SS}
D3	PMD5/RE5	H4	V_{DD}
D4	V_{SS}	H5	No Connect (NC)
D5	V_{SS}	H6	V_{DD}
D6	No Connect (NC)	H7	No Connect (NC)
D7	ETXEN/PMD14/CN15/RD6	H8	V_{BUS}
D8	ETXD3/PMD13/CN19/RD13	H9	V_{USB3V3}
D9	SDO1/OC1/INT0/RD0	H10	D+/RG2
D10	No Connect (NC)	H11	SCL2/RA2
D11	SCK1/IC3/PMCS2/PMA15/RD10	J1	AN3/C2IN+/CN5/RB3
E1	T5CK/SDI1/RC4	J2	AN2/C2IN-/CN4/RB2

Note 1: This pin is not available on PIC32MX764F128L devices.
2: Shaded pins are 5V tolerant.

2.0 GUIDELINES FOR GETTING STARTED WITH 32-BIT MCUS

Note: This data sheet summarizes the features of the PIC32MX5XX/6XX/7XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the related section of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

2.1 Basic Connection Requirements

Getting started with the PIC32MX5XX/6XX/7XX family of 32-bit Microcontrollers (MCUs) requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and VSS pins (see **2.2 "Decoupling Capacitors"**)
- All AVDD and AVSS pins even if the ADC module is not used (see **2.2 "Decoupling Capacitors"**)
- VCAP pin (see **2.3 "Capacitor on Internal Voltage Regulator (VCAP)"**)
- MCLR pin (see **2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes (see **2.5 "ICSP Pins"**)
- OSC1 and OSC2 pins when external oscillator source is used (see **2.8 "External Oscillator Pins"**)

The following pin may be required, as well: VREF+/VREF- pins used when external voltage reference for ADC module is implemented.

Note: The AVDD and AVSS pins must be connected, regardless of the ADC use and the ADC voltage reference source.

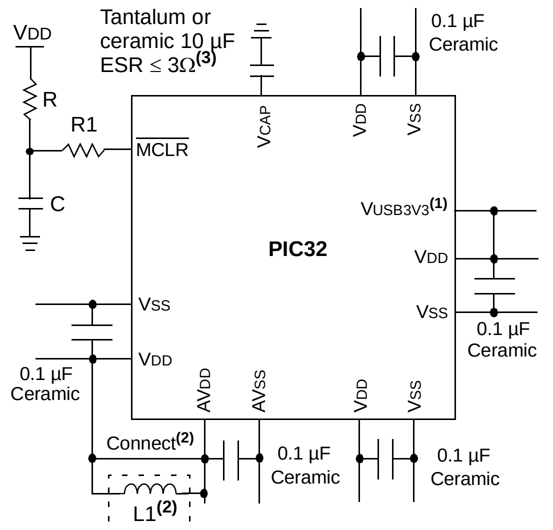
2.2 Decoupling Capacitors

The use of decoupling capacitors on power supply pins, such as VDD, VSS, AVDD and AVSS is required. See Figure 2-1.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A value of 0.1 µF (100 nF), 10-20V is recommended. The capacitor should be a low Equivalent Series Resistance (low-ESR) capacitor and have resonance frequency in the range of 20 MHz and higher. It is further recommended to use ceramic capacitors.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended that the capacitors be placed on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high frequency noise:** If the board is experiencing high frequency noise, upward of tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB track inductance.

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



Note 1: If the USB module is not used, this pin must be connected to VDD.

2: As an option, instead of a hard-wired connection, an inductor (L1) can be substituted between VDD and AVDD to improve ADC noise rejection. The inductor impedance should be less than 3Ω and the inductor capacity greater than 10 mA.

Where:

$$f = \frac{F_{CNV}}{2}$$ (i.e., ADC conversion rate/2)

$$f = \frac{1}{(2\pi\sqrt{LC})}$$

$$L = \left(\frac{1}{(2\pi f\sqrt{C})}\right)^2$$

3: Aluminum or electrolytic capacitors should not be used. ESR ≤ 3Ω from -40ºC to 125ºC @ SYSCLK frequency (i.e., MIPS).

2.2.1 BULK CAPACITORS

The use of a bulk capacitor is recommended to improve power supply stability. Typical values range from 4.7 µF to 47 µF. This capacitor should be located as close to the device as possible.

2.3 Capacitor on Internal Voltage Regulator (VCAP)

2.3.1 INTERNAL REGULATOR MODE

A low-ESR (1 ohm) capacitor is required on the VCAP pin, which is used to stabilize the internal voltage regulator output. The VCAP pin must not be connected to VDD, and must have a CEFC capacitor, with at least a 6V rating, connected to ground. The type can be ceramic or tantalum. Refer to **Section 32.0 “Electrical Characteristics”** for additional information on CEFC specifications.

2.4 Master Clear ($\overline{\text{MCLR}}$) Pin

The $\overline{\text{MCLR}}$ pin provides two specific device functions:

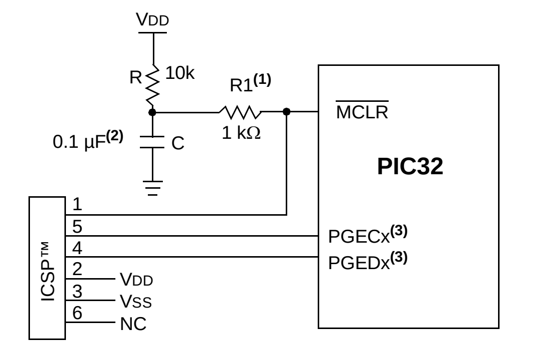
- Device Reset
- Device Programming and Debugging

Pulling The $\overline{\text{MCLR}}$ pin low generates a device Reset. Figure 2-2 illustrates a typical $\overline{\text{MCLR}}$ circuit. During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the $\overline{\text{MCLR}}$ pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as illustrated in Figure 2-2, it is recommended that the capacitor C, be isolated from the $\overline{\text{MCLR}}$ pin during programming and debugging operations.

Place the components illustrated in Figure 2-2 within one-quarter inch (6 mm) from the $\overline{\text{MCLR}}$ pin.

FIGURE 2-2: EXAMPLE OF $\overline{\text{MCLR}}$ PIN CONNECTIONS



Note 1: 470Ω ≤ R1 ≤ 1kΩ will limit any current flowing into $\overline{\text{MCLR}}$ from the external capacitor C, in the event of $\overline{\text{MCLR}}$ pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the $\overline{\text{MCLR}}$ pin VIH and VIL specifications are met without interfering with the Debug/Programmer tools.

2: The capacitor can be sized to prevent unintentional Resets from brief glitches or to extend the device Reset period during POR.

3: No pull-ups or bypass capacitors are allowed on active debug/program PGECx/PGEDx pins.

2.9 Configuration of Analog and Digital Pins During ICSP Operations

If MPLAB ICD 3 or REAL ICE is selected as a debugger, it automatically initializes all of the Analog-to-Digital input pins (ANx) as "digital" pins by setting all bits in the AD1PCFG register.

The bits in this register that correspond to the Analog-to-Digital pins that are initialized by MPLAB ICD 3 or REAL ICE, must not be cleared by the user application firmware; otherwise, communication errors will result between the debugger and the device.

If your application needs to use certain ADC pins as analog input pins during the debug session, the user application must clear the corresponding bits in the AD1PCFG register during initialization of the ADC module.

When MPLAB ICD 3 or REAL ICE is used as a programmer, the user application firmware must correctly configure the AD1PCFG register. Automatic initialization of this register is only done during debugger operation. Failure to correctly configure the register(s) will result in all ADC pins being recognized as analog input pins, resulting in the port value being read as a logic '0', which may affect user application functionality.

2.10 Unused I/Os

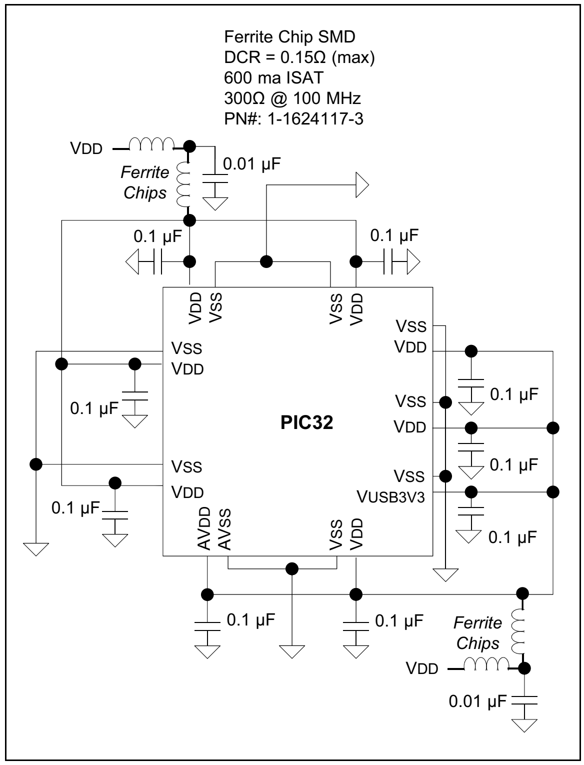
Unused I/O pins should not be allowed to float as inputs. They can be configured as outputs and driven to a logic-low state.

Alternatively, inputs can be reserved by connecting the pin to Vss through a 1k to 10k resistor and configuring the pin as an input.

2.11 EMI/EMC/EFT (IEC 61000-4-4 and IEC 61000-4-2) Suppression Considerations

The use of LDO regulators is preferred to reduce overall system noise and provide a cleaner power source. However, when utilizing switching Buck/Boost regulators as the local power source for PIC32 devices, as well as in electrically noisy environments or test conditions required for IEC 61000-4-4 and IEC 61000-4-2, users should evaluate the use of T-Filters (i.e., L-C-L) on the power pins, as shown in Figure 2-4. In addition to a more stable power source, use of this type of T-Filter can greatly reduce susceptibility to EMI sources and events.

FIGURE 2-4: EMI/EMC/EFT SUPPRESSION CIRCUIT



9.0 PREFETCH CACHE

Note: This data sheet summarizes the features of the PIC32MX5XX/6XX/7XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 4. "Prefetch Cache"** (DS60001119) in the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).

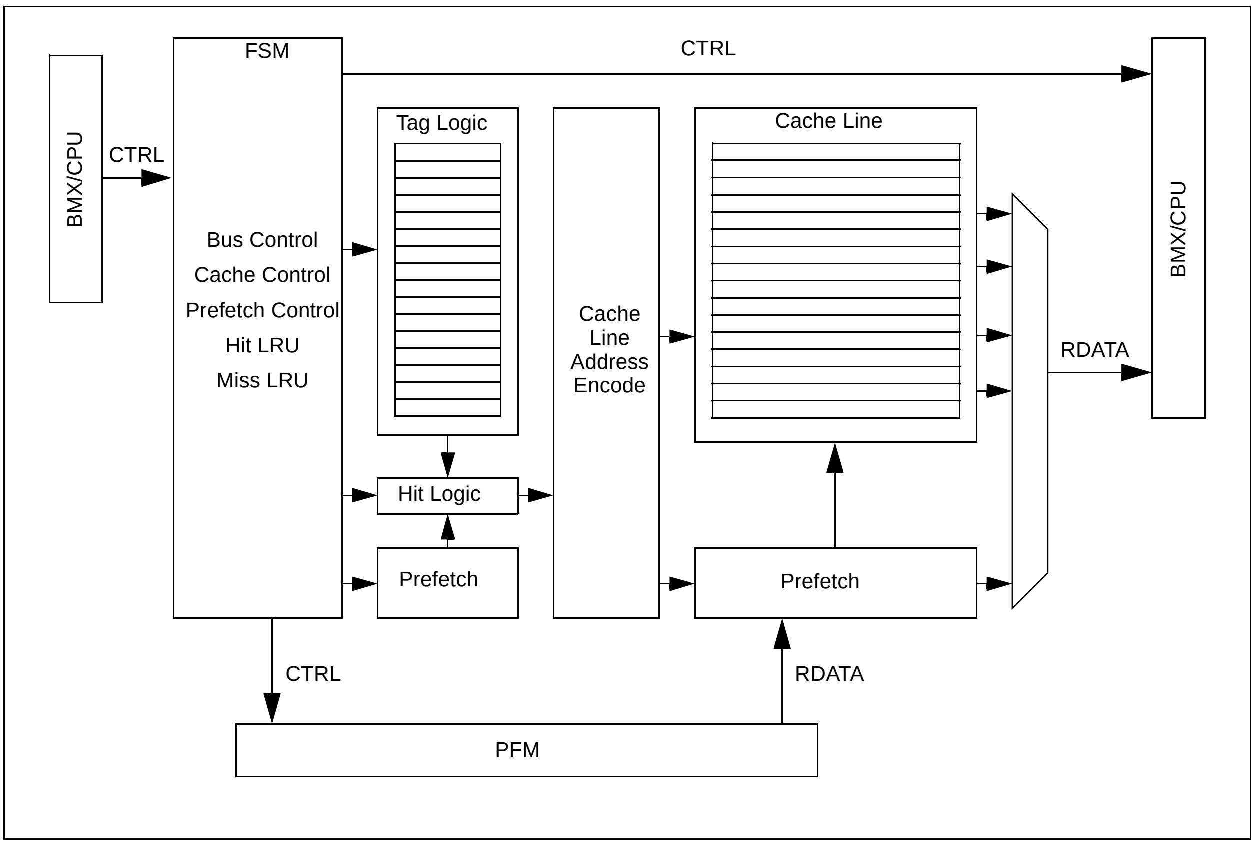
Prefetch cache increases performance for applications executing out of the cacheable program Flash memory regions by implementing instruction caching, constant data caching and instruction prefetching.

9.1 Features

- 16 fully-associative lockable cache lines
- 16-byte cache lines
- Up to four cache lines allocated to data
- Two cache lines with address mask to hold repeated instructions
- Pseudo-LRU replacement policy
- All cache lines are software writable
- 16-byte parallel memory fetch
- Predictive instruction prefetch

A simplified block diagram of the Prefetch Cache module is illustrated in Figure 9-1.

FIGURE 9-1: PREFETCH CACHE MODULE BLOCK DIAGRAM



10.1 Control Registers

TABLE 10-1: DMA GLOBAL REGISTER MAP

Virtual Address (BF88_#)	Register Name	Bit Range	Bits 31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
3000	DMACON(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	—	SUSPEND	DMABUSY	—	—	—	—	—	—	—	—	—	—	—	0000
3010	DMASTAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RDWR	DMACH<2:0>(2)			0000
3020	DMAADDR	31:16	DMAADDR<31:0>																0000
		15:0																	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

2: DMACH<3> bit is not available on PIC32MX534/564/664/764 devices.

TABLE 10-2: DMA CRC REGISTER MAP(1)

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits 31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
3030	DCRCCON	31:16	—	—	BYTO<1:0>		WBO	—	—	BITO	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	PLEN<4:0>					CRCEN	CRCAPP	CRCTYP	—	—	CRCCH<2:0>			0000
3040	DCRCDATA	31:16	DCRCDATA<31:0>																0000
		15:0																	0000
3050	DCRCXOR	31:16	DCRCXOR<31:0>																0000
		15:0																	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

REGISTER 11-8: U1EIR: USB ERROR INTERRUPT STATUS REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS
	BTSEF	BMXEF	DMAEF(1)	BTOEF(2)	DFN8EF	CRC16EF	CRC5EF(4) EOFEF(3,5)	PIDEF

Legend:	WC = Write '1' to clear	HS = Hardware Settable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7 **BTSEF:** Bit Stuff Error Flag bit
1 = Packet is rejected due to bit stuff error
0 = Packet is accepted

bit 6 **BMXEF:** Bus Matrix Error Flag bit
1 = Invalid base address of the BDT, or the address of an individual buffer pointed to by a BDT entry
0 = No address error

bit 5 **DMAEF:** DMA Error Flag bit(1)
1 = USB DMA error condition detected
0 = No DMA error

bit 4 **BTOEF:** Bus Turnaround Time-Out Error Flag bit(2)
1 = Bus turnaround time-out has occurred
0 = No bus turnaround time-out

bit 3 **DFN8EF:** Data Field Size Error Flag bit
1 = Data field received is not an integral number of bytes
0 = Data field received is an integral number of bytes

bit 2 **CRC16EF:** CRC16 Failure Flag bit
1 = Data packet is rejected due to CRC16 error
0 = Data packet is accepted

bit 1 **CRC5EF:** CRC5 Host Error Flag bit(4)
1 = Token packet is rejected due to CRC5 error
0 = Token packet is accepted
EOFEF: EOF Error Flag bit(3,5)
1 = EOF error condition is detected
0 = No EOF error condition

bit 0 **PIDEF:** PID Check Failure Flag bit
1 = PID check is failed
0 = PID check is passed

Note 1: This type of error occurs when the module's request for the DMA bus is not granted in time to service the module's demand for memory, resulting in an overflow or underflow condition, and/or the allocated buffer size is not sufficient to store the received data packet causing it to be truncated.

2: This type of error occurs when more than 16-bit-times of Idle from the previous End-of-Packet (EOP) has elapsed.

3: This type of error occurs when the module is transmitting or receiving data and the SOF counter has reached zero.

4: Device mode.

5: Host mode.

12.1 Parallel I/O (PIO) Ports

All port pins have three registers (TRIS, LAT and PORT) that are directly associated with their operation.

TRIS is a Data Direction or Tri-State Control register that determines whether a digital pin is an input or an output. Setting a TRISx register bit = 1, configures the corresponding I/O pin as an input; setting a TRISx register bit = 0, configures the corresponding I/O pin as an output. All port I/O pins are defined as inputs after a device Reset. Certain I/O pins are shared with analog peripherals and default to analog inputs after a device Reset.

PORT is a register used to read the current state of the signal applied to the port I/O pins. Writing to a PORTx register performs a write to the port's latch, LATx register, latching the data to the port's I/O pins.

LAT is a register used to write data to the port I/O pins. The LATx Latch register holds the data written to either the LATx or PORTx registers. Reading the LATx Latch register reads the last value written to the corresponding PORT or Latch register.

Not all port I/O pins are implemented on some devices, therefore, the corresponding PORTx, LATx and TRISx register bits will read as zeros.

12.1.1 CLR, SET AND INV REGISTERS

Every I/O module register has a corresponding Clear (CLR), Set (SET) and Invert (INV) register designed to provide fast atomic bit manipulations. As the name of the register implies, a value written to a SET, CLR or INV register effectively performs the implied operation, but only on the corresponding base register and only bits specified as '1' are modified. Bits specified as '0' are not modified.

Reading SET, CLR and INV registers returns undefined values. To see the affects of a write operation to a SET, CLR or INV register, the base register must be read.

> **Note:** Using a PORTxINV register to toggle a bit is recommended because the operation is performed in hardware atomically, using fewer instructions, as compared to the traditional read-modify-write method, as follows:
>
> `PORTC ^ = 0x0001;`

12.1.2 DIGITAL INPUTS

Pins are configured as digital inputs by setting the corresponding TRIS register bits = 1. When configured as inputs, they are either TTL buffers or Schmitt Triggers. Several digital pins share functionality with analog inputs and default to the analog inputs at POR. Setting the corresponding bit in the AD1PCFG register = 1 enables the pin as a digital pin.

The maximum input voltage allowed on the input pins is the same as the maximum V_{IH} specification. Refer to **Section 32.0 "Electrical Characteristics"** for V_{IH} specification details.

> **Note:** Analog levels on any pin that is defined as a digital input (including the ANx pins) may cause the input buffer to consume current that exceeds the device specifications.

12.1.3 ANALOG INPUTS

Certain pins can be configured as analog inputs used by the ADC and comparator modules. Setting the corresponding bits in the AD1PCFG register = 0 enables the pin as an analog input pin and must have the corresponding TRIS bit set = 1 (input). If the TRIS bit is cleared = 0 (output), the digital output level (V_{OH} or V_{OL}) will be converted. Any time a port I/O pin is configured as analog, its digital input is disabled and the corresponding PORTx register bit will read '0'. The AD1PCFG register has a default value of 0x0000; therefore, all pins that share ANx functions are analog (not digital) by default.

12.1.4 DIGITAL OUTPUTS

Pins are configured as digital outputs by setting the corresponding TRIS register bits = 0. When configured as digital outputs, these pins are CMOS drivers or can be configured as open-drain outputs by setting the corresponding bits in the Open-Drain Configuration (ODCx) register.

The open-drain feature allows generation of outputs higher than V_{DD} (e.g., 5V) on any desired 5V tolerant pins by using external pull-up resistors. The maximum open-drain voltage allowed is the same as the maximum V_{IH} specification.

See the **"Device Pin Tables"** section for the available pins and their functionality.

12.1.5 ANALOG OUTPUTS

Certain pins can be configured as analog outputs, such as the CV_{REF} output voltage used by the comparator module. Configuring the comparator reference module to provide this output will present the analog output voltage on the pin, independent of the TRIS register setting for the corresponding pin.

12.1.6 INPUT CHANGE NOTIFICATION

The input change notification function of the I/O ports (CNx) allows devices to generate interrupt requests in response to change-of-state on selected pin.

Each CNx pin also has a weak pull-up, which acts as a current source connected to the pin. The pull-ups are enabled by setting the corresponding bit in the CNPUE register.

TABLE 12-9: PORTF REGISTER MAP FOR PIC32MX534F064H, PIC32MX564F064H, PIC32MX564F128H, PIC32MX575F256H, PIC32MX575F512H, PIC32MX664F064H, PIC32MX664F128H, PIC32MX675F256H, PIC32MX675F512H, PIC32MX695F512H, PIC32MX775F256H, PIC32MX775F512H AND PIC32MX795F512H DEVICES

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
6140	TRISF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	TRISF5	TRISF4	TRISF3	—	TRISF1	TRISF0	003B
6150	PORTF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	RF5	RF4	RF3	—	RF1	RF0	xxxx
6160	LATF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	LATF5	LATF4	LATF3	—	LATF1	LATF0	xxxx
6170	ODCF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	ODCF5	ODCF4	ODCF3	—	ODCF1	ODCF0	0000

Legend: x = unknown value on Reset; — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

TABLE 12-10: PORTF REGISTER MAP PIC32MX534F064L, PIC32MX564F064L, PIC32MX564F128L, PIC32MX575F256L, PIC32MX575F512L, PIC32MX664F064L, PIC32MX664F128L, PIC32MX675F256L, PIC32MX675F512L, PIC32MX695F512L, PIC32MX775F256L, PIC32MX764F128L, PIC32MX775F512L AND PIC32MX795F512L DEVICES

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
6140	TRISF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	TRISF13	TRISF12	—	—	—	TRISF8	—	—	TRISF5	TRISF4	TRISF3	TRISF2	TRISF1	TRISF0	313F
6150	PORTF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	RF13	RF12	—	—	—	RF8	—	—	RF5	RF4	RF3	RF2	RF1	RF0	xxxx
6160	LATF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	LATF13	LATF12	—	—	—	LATF8	—	—	LATF5	LATF4	LATF3	LATF2	LATF1	LATF0	xxxx
6170	ODCF	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	ODCF13	ODCF12	—	—	—	ODCF8	—	—	ODCF5	ODCF4	ODCF3	ODCF2	ODCF1	ODCF0	0000

Legend: x = unknown value on Reset; — = unimplemented, read as ‘0’. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

REGISTER 24-2: CiCFG: CAN BAUD RATE CONFIGURATION REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
	—	WAKFIL	—	—	—	SEG2PH<2:0>[1,4]		
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	SEG2PHTS[1]	SAM[2]	SEG1PH<2:0>			PRSEG<2:0>		
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	SJW<1:0>[3]		BRP<5:0>					

Legend:	HC = Hardware Clear	S = Settable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-23 **Unimplemented:** Read as ‘0’

bit 22 **WAKFIL:** CAN Bus Line Filter Enable bit
1 = Use CAN bus line filter for wake-up
0 = CAN bus line filter is not used for wake-up

bit 21-19 **Unimplemented:** Read as ‘0’

bit 18-16 **SEG2PH<2:0>:** Phase Buffer Segment 2 bits[1,4]
111 = Length is 8 x T_Q
•
•
•
000 = Length is 1 x T_Q

bit 15 **SEG2PHTS:** Phase Segment 2 Time Select bit[1]
1 = Freely programmable
0 = Maximum of SEG1PH or Information Processing Time, whichever is greater

bit 14 **SAM:** Sample of the CAN Bus Line bit[2]
1 = Bus line is sampled three times at the sample point
0 = Bus line is sampled once at the sample point

bit 13-11 **SEG1PH<2:0>:** Phase Buffer Segment 1 bits[4]
111 = Length is 8 x T_Q
•
•
•
000 = Length is 1 x T_Q

Note 1: SEG2PH ≤ SEG1PH. If SEG2PHTS is clear, SEG2PH will be set automatically.
2: 3 Time bit sampling is not allowed for BRP < 2.
3: SJW ≤ SEG2PH.
4: The Time Quanta per bit must be greater than 7 (that is, $T_{QBIT} > 7$).

Note:	This register can only be modified when the CAN module is in Configuration mode (OPMOD<2:0> (CiCON<23:21>) = 100).

REGISTER 24-17: CiFLTCON7: CAN FILTER CONTROL REGISTER 7

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	FLTEN31	MSEL31<1:0>		FSEL31<4:0>				
23:16	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	FLTEN30	MSEL30<1:0>		FSEL30<4:0>				
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	FLTEN29	MSEL29<1:0>		FSEL29<4:0>				
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	FLTEN28	MSEL28<1:0>		FSEL28<4:0>				

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31 **FLTEN31:** Filter 31 Enable bit
1 = Filter is enabled
0 = Filter is disabled

bit 30-29 **MSEL31<1:0>:** Filter 31 Mask Select bits
11 = Acceptance Mask 3 selected
10 = Acceptance Mask 2 selected
01 = Acceptance Mask 1 selected
00 = Acceptance Mask 0 selected

bit 28-24 **FSEL31<4:0>:** FIFO Selection bits
11111 = Message matching filter is stored in FIFO buffer 31
11110 = Message matching filter is stored in FIFO buffer 30
•
•
•
00001 = Message matching filter is stored in FIFO buffer 1
00000 = Message matching filter is stored in FIFO buffer 0

bit 23 **FLTEN30:** Filter 30Enable bit
1 = Filter is enabled
0 = Filter is disabled

bit 22-21 **MSEL30<1:0>:** Filter 30Mask Select bits
11 = Acceptance Mask 3 selected
10 = Acceptance Mask 2 selected
01 = Acceptance Mask 1 selected
00 = Acceptance Mask 0 selected

bit 20-16 **FSEL30<4:0>:** FIFO Selection bits
11111 = Message matching filter is stored in FIFO buffer 31
11110 = Message matching filter is stored in FIFO buffer 30
•
•
•
00001 = Message matching filter is stored in FIFO buffer 1
00000 = Message matching filter is stored in FIFO buffer 0

Note: The bits in this register can only be modified if the corresponding filter enable (FLTENn) bit is ‘0’.

25.1 Control Registers

TABLE 25-5: ETHERNET CONTROLLER REGISTER SUMMARY FOR PIC32MX664F064H, PIC32MX664F128H, PIC32MX664F064L, PIC32MX664F128L, PIC32MX675F256H, PIC32MX675F512H, PIC32MX695F512H, PIC32MX775F256H, PIC32MX775F512H, PIC32MX795F512H, PIC32MX695F512L, PIC32MX675F256L, PIC32MX675F512L, PIC32MX764F128H, PIC32MX764F128L, PIC32MX775F256L, PIC32MX775F512L AND PIC32MX795F512L DEVICES

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
9000	ETHCON1	31:16	PTV<15:0>																0000
		15:0	ON	—	SIDL	—	—	—	TXRTS	RXEN	AUTOFC	—	—	MANFC	—	—	—	BUFCDEC	0000
9010	ETHCON2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	RXBUFSZ<6:0>							—	—	—	—	0000
9020	ETHTXST	31:16	TXSTADDR<31:16>																0000
		15:0	TXSTADDR<15:2>														—	—	0000
9030	ETHRXST	31:16	RXSTADDR<31:16>																0000
		15:0	RXSTADDR<15:2>														—	—	0000
9040	ETHHT0	31:16	HT<31:0>																0000
		15:0																	0000
9050	ETHHT1	31:16	HT<63:32>																0000
		15:0																	0000
9060	ETHPMM0	31:16	PMM<31:0>																0000
		15:0																	0000
9070	ETHPMM1	31:16	PMM<63:32>																0000
		15:0																	0000
9080	ETHPMCS	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	PMCS<15:0>																0000
9090	ETHPMO	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	PMO<15:0>																0000
90A0	ETHRXFC	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	HTEN	MPEN	—	NOTPM	PMMODE<3:0>				CRC ERREN	CRC OKEN	RUNT ERREN	RUNTEN	UCEN	NOT MEEN	MCEN	BCEN	0000
90B0	ETHRXWM	31:16	—	—	—	—	—	—	—	—	RXFWM<7:0>								0000
		15:0	—	—	—	—	—	—	—	—	RXEWM<7:0>								0000
90C0	ETHIEN	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	TX BUSEIE	RX BUSEIE	—	—	—	EW MARKIE	FW MARKIE	RX DONEIE	PK TPENDIE	RX ACTIE	—	TX DONEIE	TX ABORTIE	RX BUFNAIE	RX OVFLWIE	0000
90D0	ETHIRQ	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	TXBUSE	RXBUSE	—	—	—	EWMARK	FWMARK	RXDONE	PKTPEND	RXACT	—	TXDONE	TXABORT	RXBUFNA	RXOVFLW	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table (with the exception of ETHSTAT) have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

2: Reset values default to the factory programmed value.

REGISTER 25-14: ETHIRQ: ETHERNET CONTROLLER INTERRUPT REQUEST REGISTER

bit 6 **PKTPEND:** Packet Pending Interrupt bit
1 = RX packet pending in memory
0 = RX packet is not pending in memory
This bit is set when the BUFCNT counter has a value other than '0'. It is cleared by either a Reset or by writing the BUFCDEC bit to decrement the BUFCNT counter. Writing a '0' or a '1' has no effect.

bit 5 **RXACT:** Receive Activity Interrupt bit
1 = RX packet data was successfully received
0 = No interrupt pending
This bit is set whenever RX packet data is stored in the RXBM FIFO. It is cleared by either a Reset or CPU write of a '1' to the CLR register.

bit 4 **Unimplemented:** Read as '0'

bit 3 **TXDONE:** Transmit Done Interrupt bit
1 = TX packet was successfully sent
0 = No interrupt pending
This bit is set when the currently transmitted TX packet completes transmission, and the Transmit Status Vector is loaded into the first descriptor used for the packet. It is cleared by either a Reset or CPU write of a '1' to the CLR register.

bit 2 **TXABORT:** Transmit Abort Condition Interrupt bit
1 = TX abort condition occurred on the last TX packet
0 = No interrupt pending
This bit is set when the MAC aborts the transmission of a TX packet for one of the following reasons:

- Jumbo TX packet abort
- Underrun abort
- Excessive defer abort
- Late collision abort
- Excessive collisions abort

This bit is cleared by either a Reset or CPU write of a '1' to the CLR register.

bit 1 **RXBUFNA:** Receive Buffer Not Available Interrupt bit
1 = RX Buffer Descriptor Not Available condition has occurred
0 = No interrupt pending
This bit is set by a RX Buffer Descriptor Overrun condition. It is cleared by either a Reset or a CPU write of a '1' to the CLR register.

bit 0 **RXOVFLW:** Receive FIFO Over Flow Error bit
1 = RX FIFO Overflow Error condition has occurred
0 = No interrupt pending
RXOVFLW is set by the RXBM Logic for an RX FIFO Overflow condition. It is cleared by either a Reset or CPU write of a '1' to the CLR register.

Note: It is recommended to use the SET, CLR, or INV registers to set or clear any bit in this register. Setting or clearing any bits in this register should only be done for debug/test purposes.

REGISTER 25-25: EMAC1IPGT: ETHERNET CONTROLLER MAC BACK-TO-BACK INTERPACKET GAP REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	R/W-0	R/W-0	R/W-1	R/W-0	R/W-0	R/W-1	R/W-0
	—	B2BIPKTGP<6:0>						

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-7 **Unimplemented:** Read as ‘0’

bit 6-0 **B2BIPKTGP<6:0>:** Back-to-Back Interpacket Gap bits

This is a programmable field representing the nibble time offset of the minimum possible period between the end of any transmitted packet, to the beginning of the next. In Full-Duplex mode, the register value should be the desired period in nibble times minus 3. In Half-Duplex mode, the register value should be the desired period in nibble times minus 6. In Full-Duplex the recommended setting is 0x15 (21d), which represents the minimum IPG of 0.96 µs (in 100 Mbps) or 9.6 µs (in 10 Mbps). In Half-Duplex mode, the recommended setting is 0x12 (18d), which also represents the minimum IPG of 0.96 µs (in 100 Mbps) or 9.6 µs (in 10 Mbps).

Note: Both 16-bit and 32-bit accesses are allowed to these registers (including the SET, CLR and INV registers). 8-bit accesses are not allowed and are ignored by the hardware.

TABLE 32-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD}) (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +105°C for V-Temp			
Param. No.	**Typical(2)**	**Max.**	**Units**	**Conditions**		
Power-Down Current (I_{PD})(1) for PIC32MX534/564/664/764 Family Devices						
DC40g	12	40	µA	-40°C	2.3V	Base Power-Down Current **(Note 6)**
DC40h	20	120		+25°C		
DC40i	210	600		+85°C		
DC40o	400	1000		+105°C		
DC40j	20	120		+25°C	3.3V	Base Power-Down Current
DC40k	15	80		-40°C	3.6V	Base Power-Down Current
DC40l	20	120		+25°C		
DC40m	113	350**(5)**		+70°C		
DC40n	220	650		+85°C		
DC40p	500	1000		+105°C		
Module Differential Current for PIC32MX534/564/664/764 Family Devices						
DC41c	—	10	µA	—	2.5V	Watchdog Timer Current: ΔI_{WDT} **(Notes 3,6)**
DC41d	5	—			3.3V	Watchdog Timer Current: ΔI_{WDT} **(Note 3)**
DC41e	—	20			3.6V	Watchdog Timer Current: ΔI_{WDT} **(Note 3)**
DC42c	—	40	µA	—	2.5V	RTCC + Timer1 w/32 kHz Crystal: ΔI_{RTCC} **(Notes 3,6)**
DC42d	23	—			3.3V	RTCC + Timer1 w/32 kHz Crystal: ΔI_{RTCC} **(Note 3)**
DC42e	—	50			3.6V	RTCC + Timer1 w/32 kHz Crystal: ΔI_{RTCC} **(Note 3)**
DC43c	—	1300	µA	—	2.5V	ADC: ΔI_{ADC} **(Notes 3,4,6)**
DC43d	1100	—			3.3V	ADC: ΔI_{ADC} **(Notes 3,4)**
DC43e	—	1300			3.6V	ADC: ΔI_{ADC} **(Notes 3,4)**

Note 1: The test conditions for I_{PD} current measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU is in Sleep mode, program Flash memory Wait states = `111`, Program Cache and Prefetch are disabled and SRAM data memory Wait states = `1`
- No peripheral modules are operating, (ON bit = `0`)
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{MCLR}$ = V_{DD}
- RTCC and JTAG are disabled

2: Data in the “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current.

4: Test conditions for ADC module differential current are as follows: Internal ADC RC oscillator enabled.

5: Data is characterized at +70°C and not tested. Parameter is for design guidance only.

6: This parameter is characterized, but not tested in manufacturing.

FIGURE 32-28: EJTAG TIMING CHARACTERISTICS

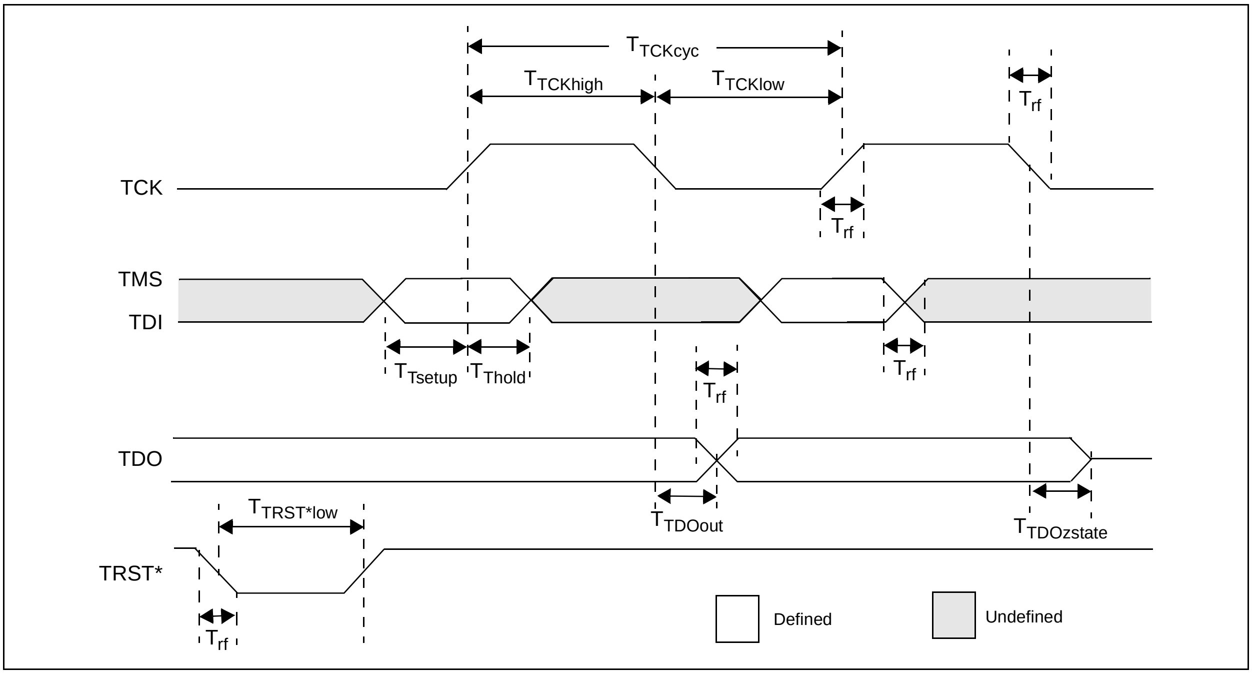


TABLE 32-43: EJTAG TIMING REQUIREMENTS

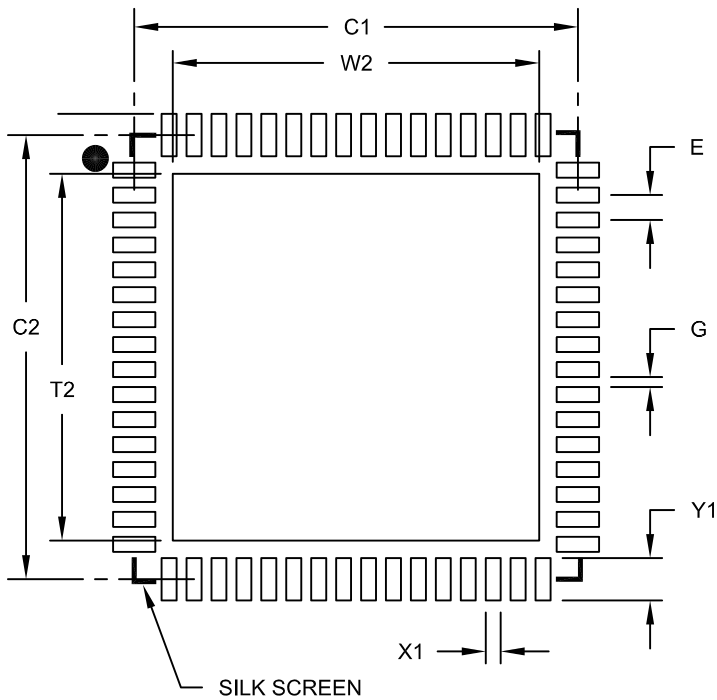
AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-Temp			
Param. No.	**Symbol**	**Description[1]**	**Min.**	**Max.**	**Units**	**Conditions**
EJ1	TTCKCYC	TCK Cycle Time	25	—	ns	—
EJ2	TTCKHIGH	TCK High Time	10	—	ns	—
EJ3	TTCKLOW	TCK Low Time	10	—	ns	—
EJ4	TTSETUP	TAP Signals Setup Time Before Rising TCK	5	—	ns	—
EJ5	TTHOLD	TAP Signals Hold Time After Rising TCK	3	—	ns	—
EJ6	TTDOOUT	TDO Output Delay Time from Falling TCK	—	5	ns	—
EJ7	TTDOZSTATE	TDO 3-State Delay Time from Falling TCK	—	5	ns	—
EJ8	TTRSTLOW	TRST Low Time	25	—	ns	—
EJ9	TRF	TAP Signals Rise/Fall Time, All Input and Output	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

NOTES:

64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body [QFN]
With 0.40 mm Contact Length

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	Units	MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Optional Center Pad Width	W2			7.35
Optional Center Pad Length	T2			7.35
Contact Pad Spacing	C1		8.90	
Contact Pad Spacing	C2		8.90	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			0.85
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2149A

S

T